

INTERNATIONAL STANDARD

**Materials for printed boards and other interconnecting structures –
Part 2-47: Reinforced base materials clad and unclad – Non-halogenated
epoxide non-woven/woven E-glass reinforced laminate sheets of thermal
conductivity 2,0 W/(m•K) and defined flammability (vertical burning test),
copper-clad for lead-free assembly**



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IEC Central Office
3, rue de Varembe
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
info@iec.ch
www.iec.ch

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FOREWORD

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International Standard IEC 61249-2-45 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this International Standard is based on the following documents:

CDV	Report on voting
91/1449/FDIS	91/1485/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of the IEC 61249 series, under the general title *Materials for printed boards and other interconnecting structures*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
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- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

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1 Scope

This part of IEC 61249 gives requirements for properties of non-halogenated epoxide non-woven reinforced core/woven E-glass reinforced surface laminate sheets of thermal conductivity and defined flammability (vertical burning test), copper-clad for lead-free assembly in thicknesses of 0,60 mm up to 1,70 mm. The flammability rating is achieved through the use of non-halogenated fire retardants reacted as part of the epoxide polymeric structure. The glass transition temperature is defined to be 105 °C minimum. Thermal conductivity is defined to be $(2,0 \pm 0,30)$ W/(m•K).

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61189-2:2006, *Test methods for electrical materials, printed boards and other interconnection structures and assemblies – Part 2: Test methods for materials for interconnection structures*

IEC 61249-5-1, *Materials for interconnection structures – Part 5: Sectional specification set for conductive foils and films with and without coatings – Section 1: Copper foils (for the manufacture of copper-clad base materials)*

IEC/PAS 61249-6-3, *Specification for finished fabric woven from "E" glass for printed boards*

ISO 11014, *Safety data sheet for chemical products – Content and order of sections*

3 Terms and definitions

No terms and definitions are listed in this document.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
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